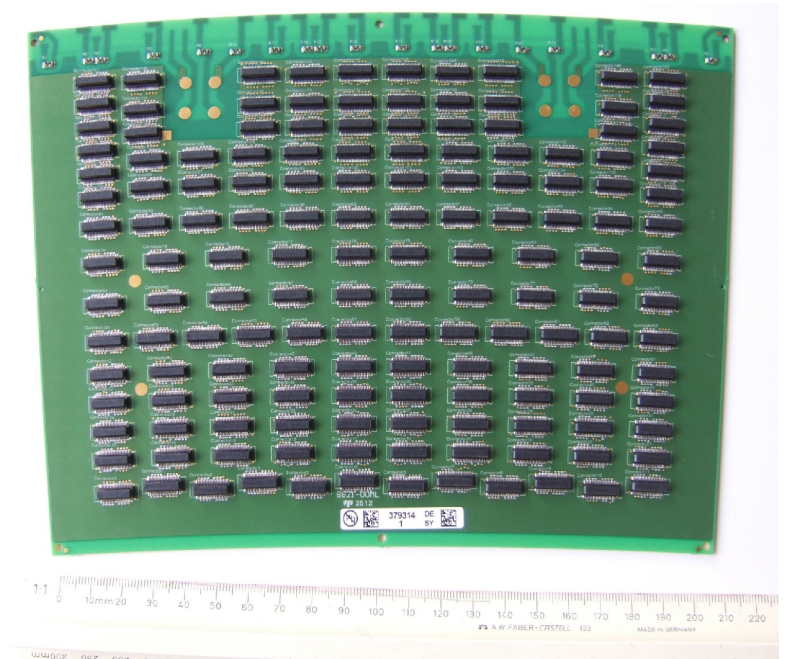
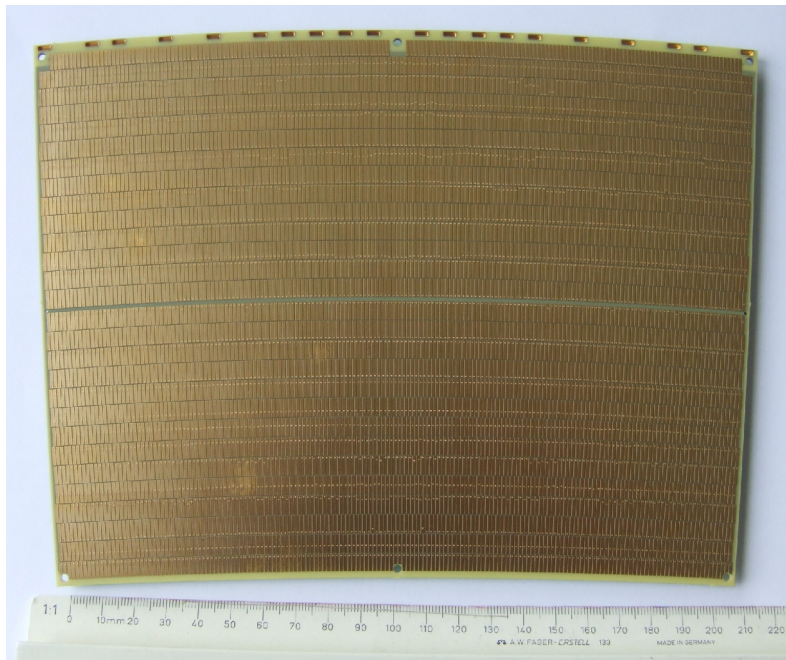


Status of DESY GEM-Module

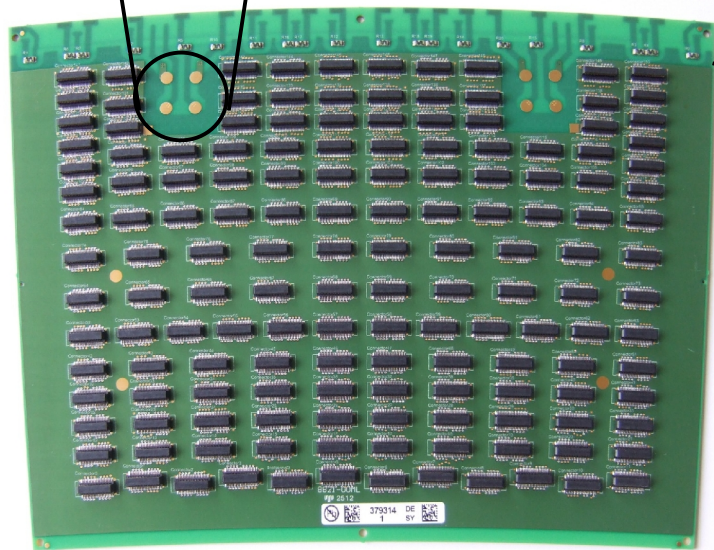
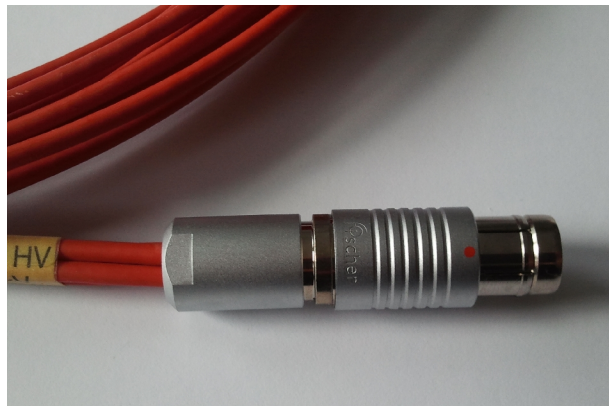
Felix Müller
LCTPC WP meeting #154
19.07.2012

New Readout Board

- Five readout boards arrived at DESY
 - Full sensitive board (4828 pads of size $1.26 \times 5.85 \text{ mm}^2$)
- Readout connectors and protection resistors were soldered to three boards



HV Distribution

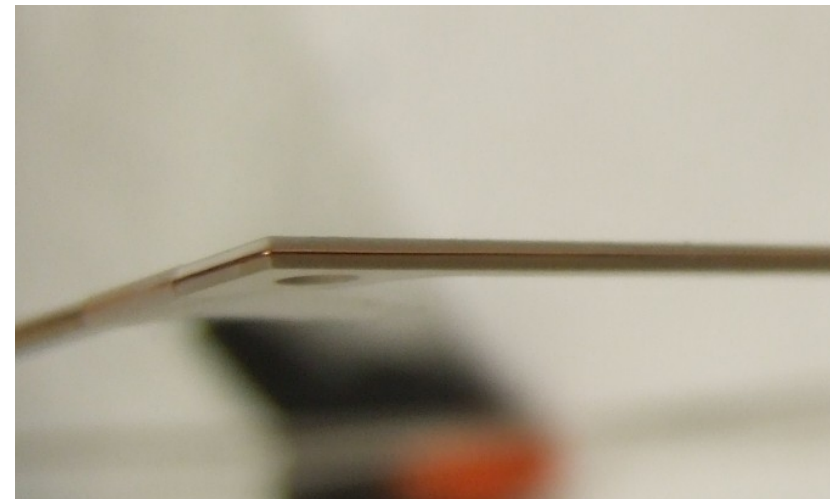
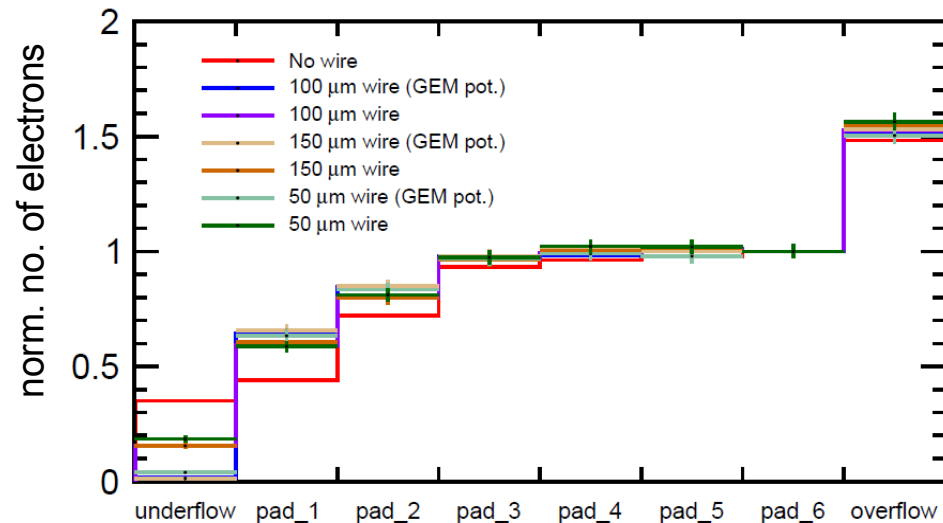
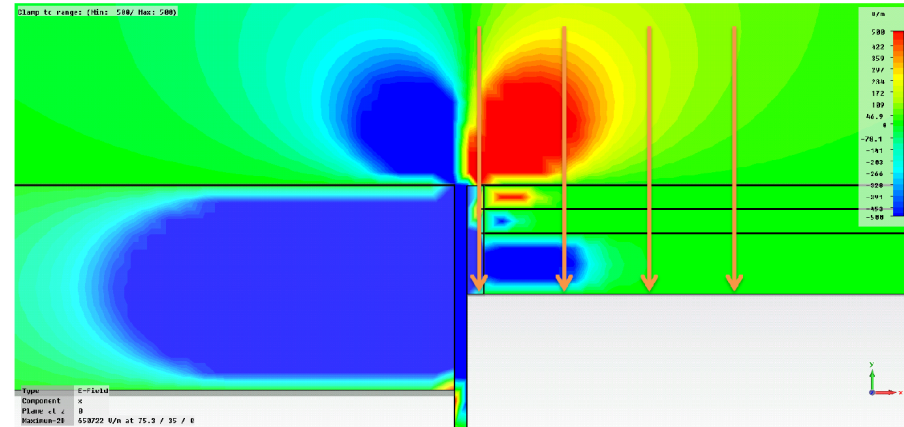


Row of protection resistors
(10 M Ω each)



Field Shaping Ring

- E-Field distortions at module edges
- Field shaping ring to form E-Field more homogeneous
- Simulations show significant increase in the collection efficiency



Status

- Three new modules in preparation
- Now
 - Field shaping ring being mounted on real GEM grid
 - GEMs being glued to grids with ring
 - Testing of boards (HV)
- Next
 - Assembly of modules
 - Testing of modules in small test box
 - Testing of modules in Large Prototype
- Testbeam campaign planned for mid/end of August

